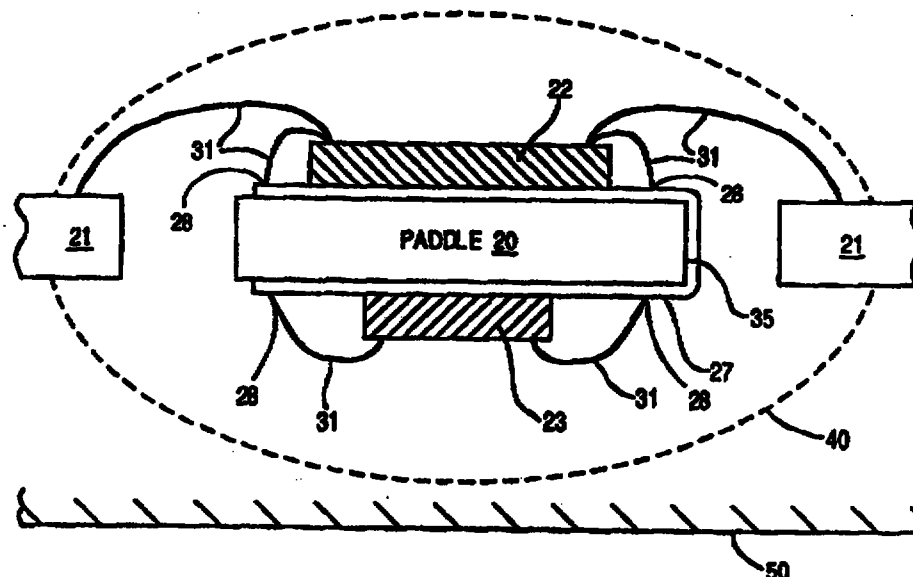


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(54) Title: A PACKAGE HOUSING MULTIPLE SEMICONDUCTOR DIES**(57) Abstract**

A package (50) housing multiple semiconductor dies (22, 23) includes a leadframe having a paddle (20) and a number of lead fingers (21). A flexible circuit (27) is adhesively laminated to both sides of the paddle. A first semiconductor die (23) is back-mounted to the bottom surface of the paddle and wire-bonded to the flexible circuit and the lead fingers. A second semiconductor die (22) is back-mounted to the top surface of the paddle and to the flexible circuit. The dies (22, 23) are encapsulated in a security coating (40) and encased in plastic (50).